

Notice of References Cited	Application/Control No. 09/854,269	Applicant(s)/Patent Under Reexamination DISTEFANO, THOMAS H.	
	Examiner Monica Lewis	Art Unit 2822	Page 1 of 1

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	B	US-5,950,073	09-1999	Griffen, IV et al.	438/119
	C	US-5,597,469	01-1997	Carey et al.	205/118
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	E	US-6,286,206	09-2001	Li	29/840
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	U	Marshall et al., 1991, IEEE, 41 st Electronic Components and Technology Conference, Pages 647-652.
	V	Marshall et al., 1997, MCB University Press, Soldering and Surface Mount Technology, Vol. 9 No. 2, Pages 1-24.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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